SPN7575
N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN7575 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

This device is particularly suited for E Bike application.

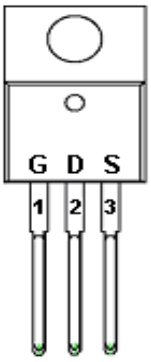
APPLICATIONS

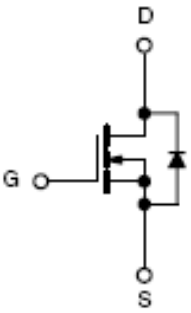
- DC/DC Converter
- Load Switch
- Power Tool

FEATURES

- 75V/80A, $R_{DS(ON)}$= 11mΩ@V_{GS}= 10V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- TO-220-3L package design

PIN CONFIGURATION(TO-220-3L)





PART MARKING

SPN7575
N-Channel Enhancement Mode MOSFET

PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN7575T220TG	TO-220-3L	SPN7575

※ SPN7575T220TG: Tube ; Pb – Free

ABSOULTE MAXIMUM RATINGS

(T_A=25℃ Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V_{DSS}	75	V
Gate –Source Voltage		V_{GSS}	±20	V
Continuous Drain Current(T_J=150℃)	T_A=25℃	I_D	90	A
	T_A=70℃		80	
Pulsed Drain Current		I_{DM}	370	A
Avalanche Current		I_{AS}	52	A
Power Dissipation	T_A=25℃	P_D	200	W
	T_A=70℃		140	
Avalanche Energy with Single Pulse (Tj=25℃, L = 500uH , I_{AS} = 20A , V_{DD} = 60V.)		EAS	165	mJ
Operating Junction Temperature		T_J	-55/150	℃
Storage Temperature Range		T_{STG}	-55/150	℃
Thermal Resistance-Junction to Ambient		$R_{\theta JC}$	0.75	℃/W

ELECTRICAL CHARACTERISTICS

(T_A=25℃ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V,I_D=250uA	75			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250uA	2.0		4.0	
Gate Leakage Current	I_{GSS}	V_{DS}=0V,V_{GS}=±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V			1	uA
		V_{DS}=60V,V_{GS}=0V T_J = 55 ℃			5	
On-State Drain Current	$I_{D(on)}$	V_{DS}≥5V,V_{GS} =10V	70			A
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}= 10V, I_D=40A		11	12	mΩ
Forward Transconductance	gfs	V_{DS}=5V,I_D=20A		52		S
Single Pulse Avalanche Energy	EAS	V_{DS}=60V, L=500uH, I_{AS}=20A	58			mJ
Diode Forward Voltage	V_{SD}	I_S=30A,V_{GS} =0V			1.2	V
Dynamic						
Total Gate Charge	Q_g	V_{DS}=15V,V_{GS}=10V I_D= 15A		105		nC
Gate-Source Charge	Q_{gs}			20		
Gate-Drain Charge	Q_{gd}			17		
Input Capacitance	C_{iss}	V_{DS}=15V,V_{GS}=0V f=1MHz		7760		pF
Output Capacitance	C_{oss}			320		
Reverse Transfer Capacitance	C_{rss}			210		
Turn-On Time	$t_{d(on)}$	V_{DD}=15V, I_D=1A, V_{GEN}=10V, R_G=3.3Ω		19.5		nS
	t_r			11.5		
Turn-Off Time	$t_{d(off)}$			118.5		
	t_f			11		

TYPICAL CHARACTERISTICS

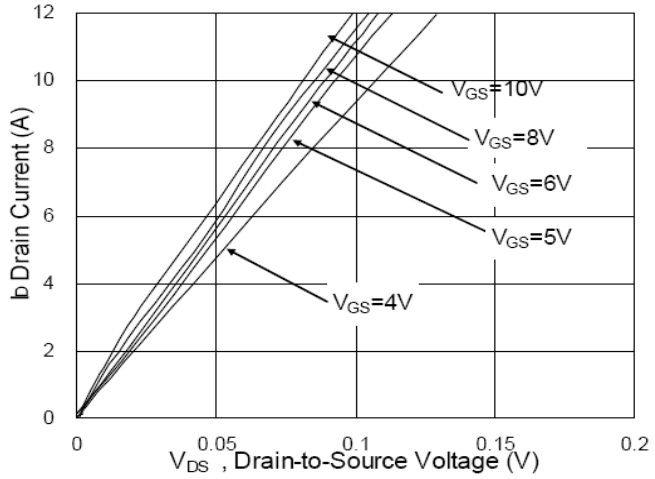


Fig. 1 Typical Output Characteristics

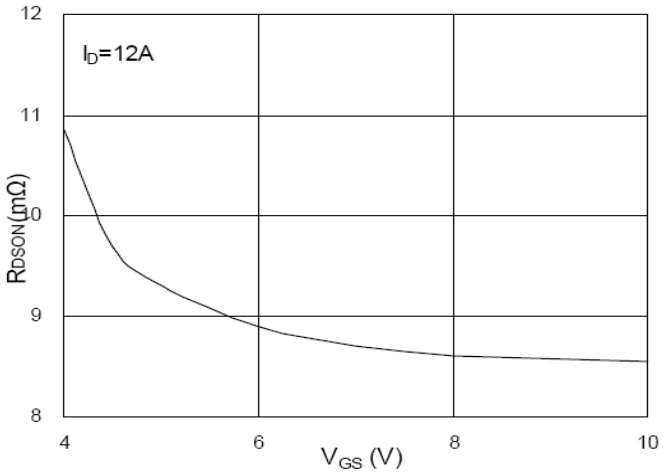


Fig. 2 On-Resistance vs. Gate Voltage

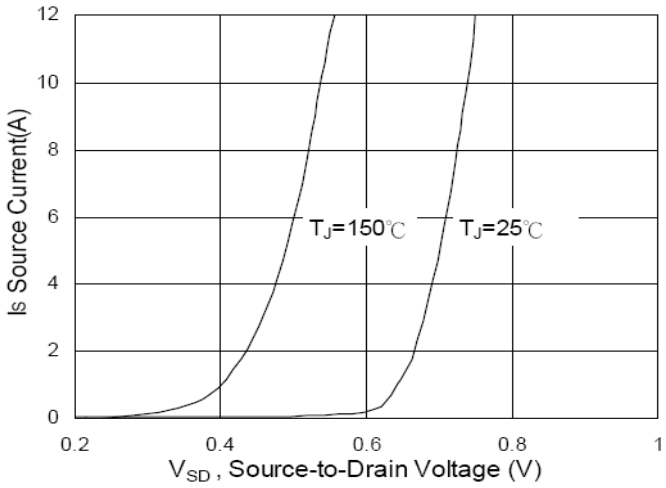


Fig. 3 Forward Characteristics of Reverse Diode

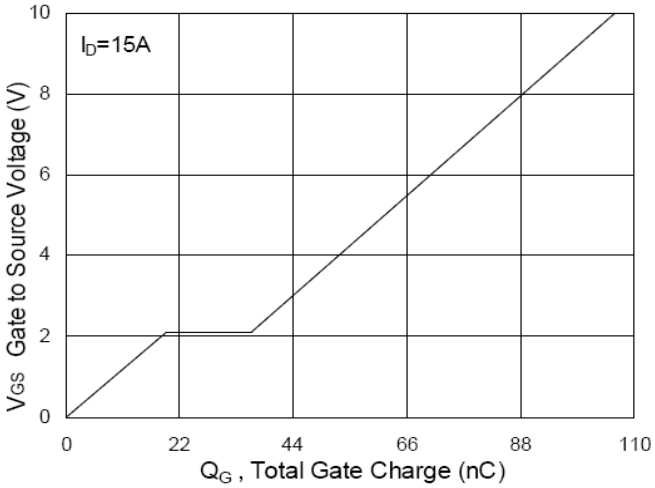


Fig. 4 Gate Charge Characteristics

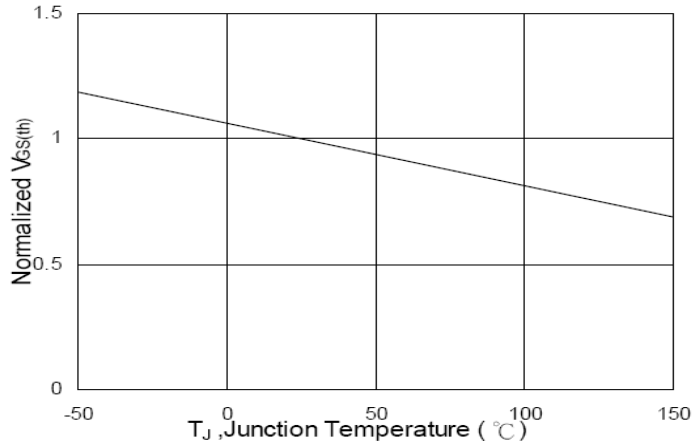


Fig. 5 Vgs vs. Junction Temperature

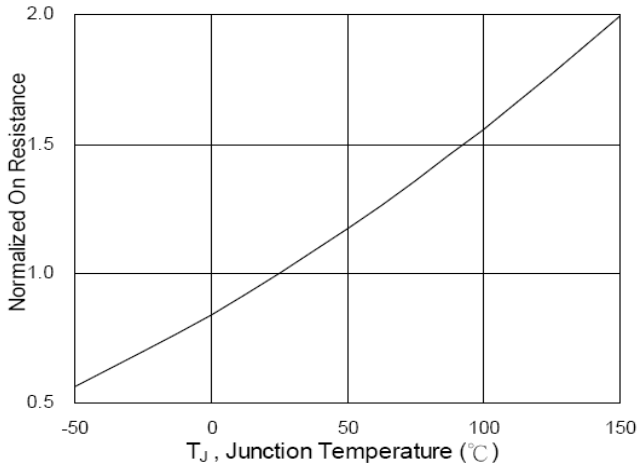


Fig. 6 On Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS

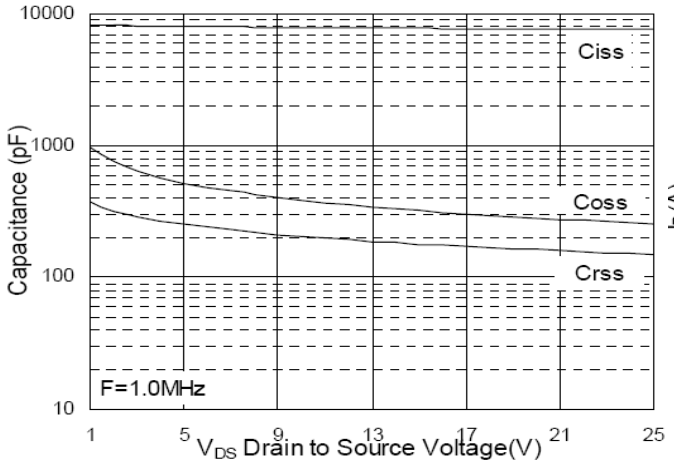


Fig. 7 Typical Capacitance Characteristics

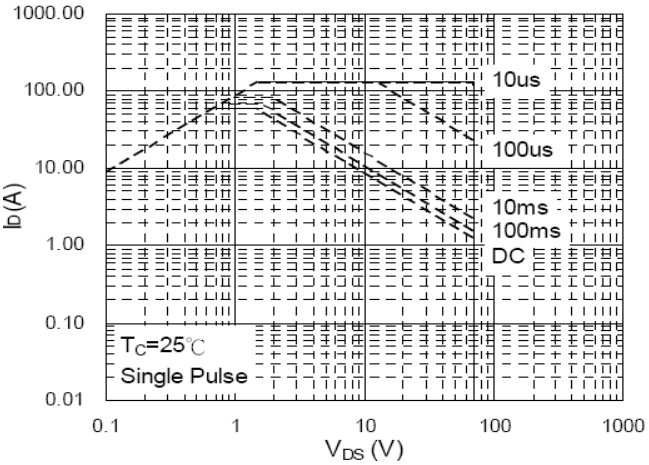


Fig. 8 Maximum Safe Operation Area

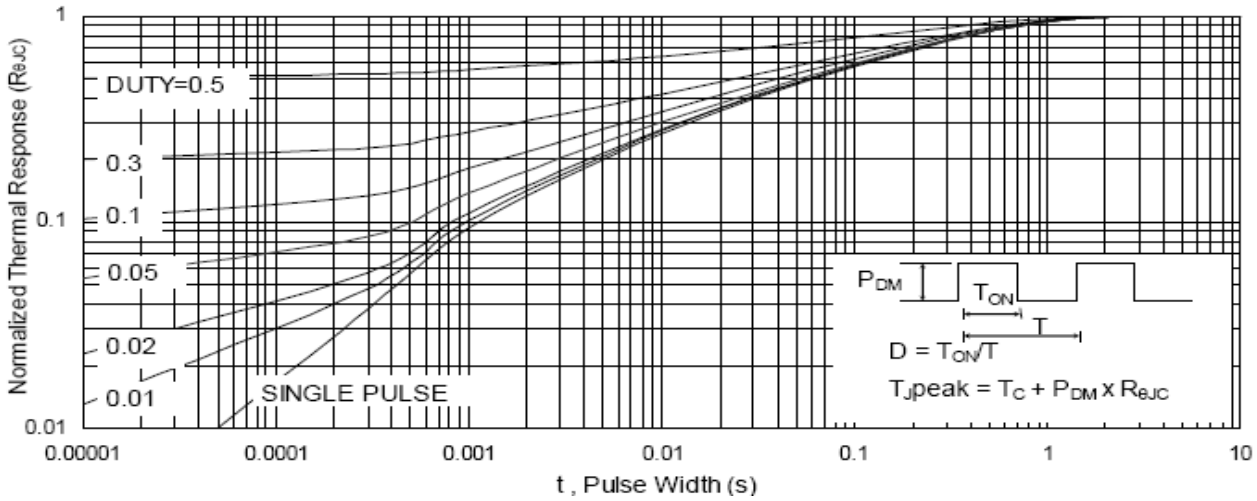


Fig. 9 Effective Transient Thermal Impedence

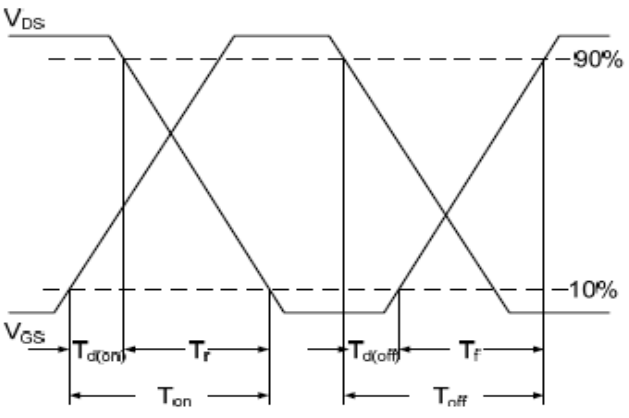


Fig. 10 Switching Time Waveform

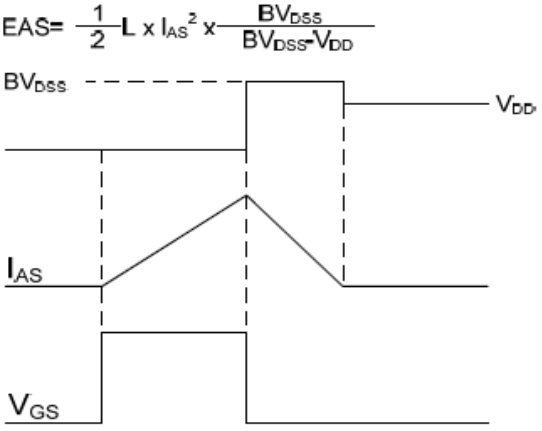
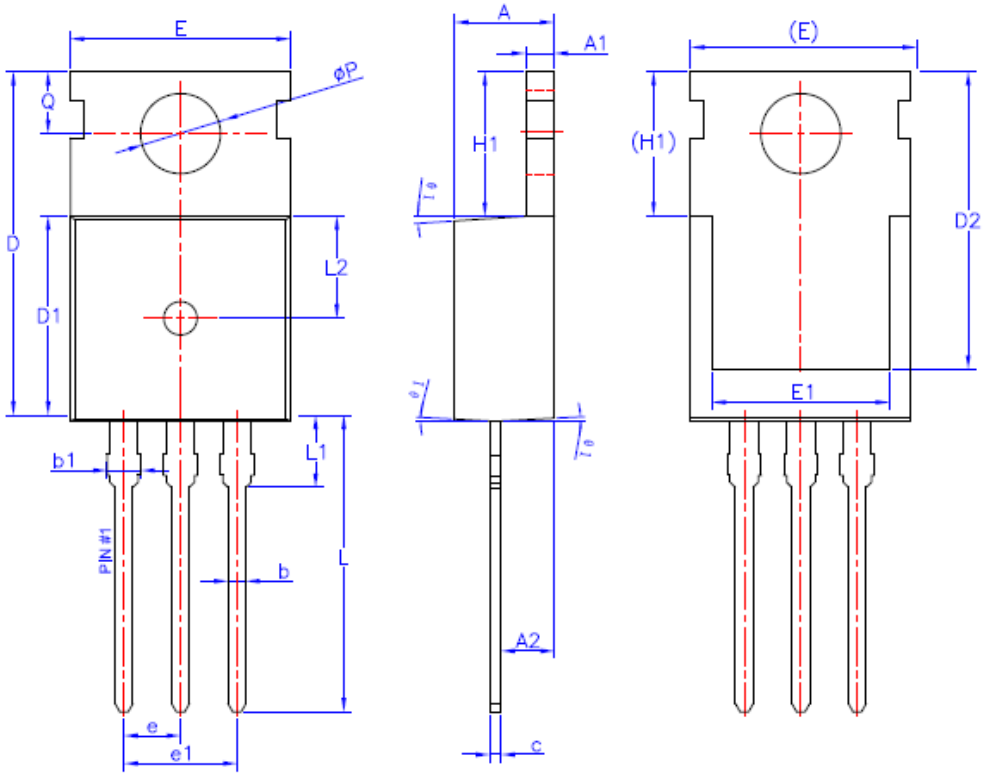


Fig. 11 Unclamped Inductive Waveform

TO-220-3L PACKAGE OUTLINE



SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	–	0.90
b1	1.42	–	1.57
c	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	–	13.70
E	9.70	9.90	10.20
E1	7.80	8.00	8.20
e	2.54BSC		
e1	5.08BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	–	–	3.50
L2	4.60REF		
ØP	3.55	3.60	3.65
Q	2.73	–	2.87
θ1	1°	3°	5°

SYNC Power Corporation
7F-2, No.3-1, Park Street
NanKang District (NKSP), Taipei, Taiwan 115
Phone: 886-2-2655-8178
Fax: 886-2-2655-8468
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